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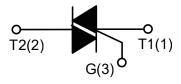
DESCRIPTION:

With high ability to withstand the shock loading of large current, BTB16-600CW series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



MAIN FEATURES

Symbol	Value	Unit
I _{T(RMS)}	16	Α
V _{DRM} /V _{RRM}	600/800/1200	V



ABSOLUTE MAXIMUM RATINGS

F	Parameter	Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40-150	$^{\circ}$ C
Operating junction temperature range		Tj	-40-125	$^{\circ}$ C
Repetitive peak off-state voltage (T _j =25℃)		V _{DRM}	600/800/1200	V
Repetitive peak reverse voltage (T _j =25℃)		V _{RRM}	600/800/1200	V
Non repetitive surge peak Off-state voltage		V _{DSM}	V _{DRM} +100	V
Non repetitive peak reverse voltage		V _{RSM}	V _{RRM} +100	V
RMS on-state current	TO-220A(Ins)/ TO-220F(Ins) (T _C =75°C) TO-220A(Non-Ins)/ TO-220C (T _C =95°C) TO-262 (T _C =70°C)	I _{T(RMS)}	16	А
Non repetitive surge peak on-state current (full cycle, F=50Hz)		I _{TSM}	160	А

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I ² t value for fusing (tp=10ms)	l ² t	128	A ² s
Critical rate of rise of on-state current $(I_G = 2 \times I_{GT})$	dl/dt	50	A/µs
Peak gate current	I _{GM}	4	Α
Average gate power dissipation	P _{G(AV)}	1	W
Peak gate power	P _{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j =25 $^{\circ}$ C unless otherwise specified)

3 Quadrants

Symbol	Test Condition Qu	Quadrant	Overdrent	Value				Unit
		Quaurant		BW	CW	sw	TW	Oilit
Ідт	V _D =12V R _L =33Ω	I - II -III	MAX	50	35	10	5	mA
V _G T	VD-12V KL-3312	I - II -III	MAX	1.3				٧
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C RL = 3.3KΩ	I - II -III	MIN	0.2			V	
IL	I _G =1.2I _{GT}	I -III	MAX	70	50	30	15	mΛ
		II	IVIAA	80	60	40	20	mA
Ін	I _T =100mA		MAX	60	40	25	15	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	1000	500	200	100	V/µs

4 Quadrants

Symbol	Test Condition Quad	Quadrant	Quadrant	Va	Unit	
		Quaurani		В	С	Ollit
lgт		I - II -III	MAX	50	25	mΛ
	V _D =12V R _L =33Ω	IV			50	mA
V _G T		ALL	MAX	1.5		V
V _{GD}	$V_D = V_{DRM} T_j = 125^{\circ}C$ $R_L = 3.3 K\Omega$	ALL	MIN	0.2		V
IL	I _G =1.2I _{GT}	I -III-IV	MAX	70	50	mA
		II	IVIAA	100	80	IIIA
Ін	I _T =100mA		MAX	60	40	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	500	200	V/µs



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STATIC CHARACTERISTICS

Cymbol	Parameter		V	Unit		
Symbol			-600V	-800V	-1200V	Offic
V _{TM}	I _{TM} =22.5A tp=380μs	T _j =25℃	1.5			V
I _{DRM}	V _D =V _{DRM} V _R =V _{RRM}	T _j =25℃	5	5	10	μA
I _{RRM}		T _j =125℃	1	1	2	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth(j-c)		TO-220A(Ins)	2.1	°C/W
	junction to case(AC)	TO-220A(Non-Ins)/ TO-220C	1.2	
		TO-220F(Ins)	2.3	
		TO-262	2.5	



FIG.1 Maximum power dissipation versus RMS on-state current

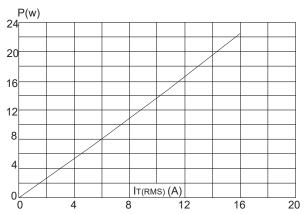


FIG.3: Surge peak on-state current versus number of cycles

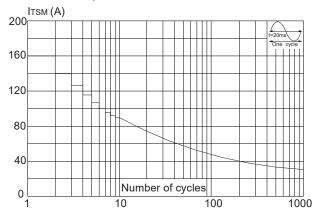


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I²t (dI/dt < 50A/µs)

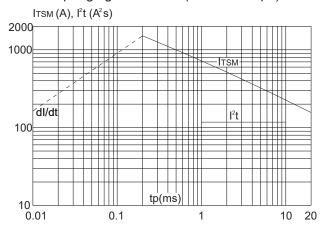


FIG.2: RMS on-state current versus case temperature



FIG.4: On-state characteristics (maximum values)

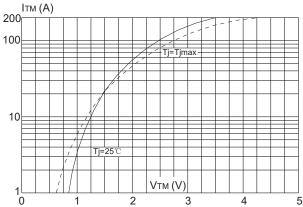


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

